

REMARKS

The specification has been amended to correct errors of a typographical and grammatical nature. Due to the number of corrections thereto, applicants submit herewith a Substitute Specification, along with a marked-up copy of the original specification for the Examiner's convenience. The substitute specification includes the changes as shown in the marked-up copy and includes no new matter. Therefore, entry of the Substitute Specification is respectfully requested.

The abstract has also been amended to more clearly describe the features of the present invention.

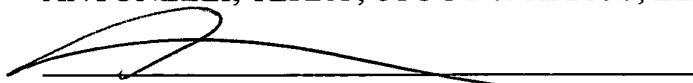
Also submitted herewith is a proposed amendment to the drawings, wherein Figs. 5, 19, 20, 21, 22, 24, 25, 27, 28, 30 and 31 have been amended at this time. Upon receipt of the approval of the amendment to the drawings and receipt of a Notice of Allowance, the proposed drawing corrections will be effected in accordance with present practice.

Entry of the preliminary amendments and examination of the application is respectfully requested.

To the extent necessary, applicant's petition for an extension of time under 37 CFR 1.136. Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account No. 01-2135 (501.40792VX1) and please credit any excess fees to such deposit account.

Respectfully submitted,

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Abstract of the Disclosure

A multi-chip module ~~including~~ has semiconductor devices and a wiring substrate for mounting the semiconductor devices, in which the wiring substrate comprises a glass substrate having holes formed by sand blasting and a wiring layer formed on the surface of the glass substrate and having wiring and an insulation layer.